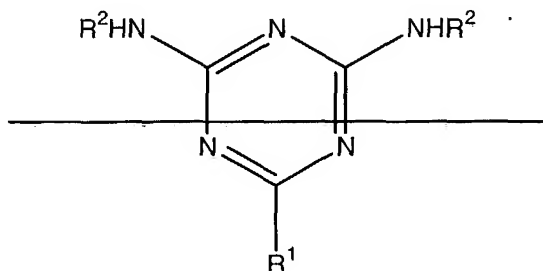
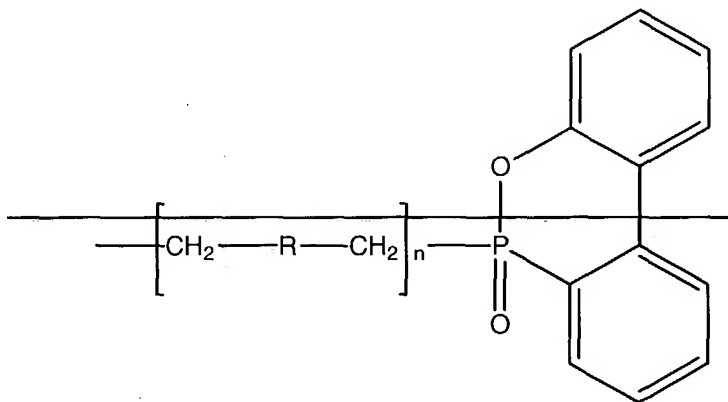


Listing of Claims

1. (Currently Amended) A phosphorus- and nitrogen-containing resin hardener, which has a structure represented by the following formula:

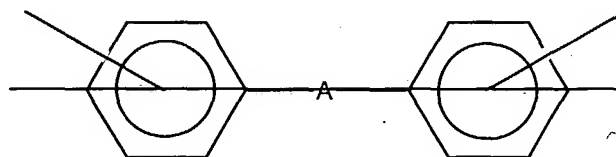


wherein R^2 represents a hydrogen atom, or a group represented by the following formula:

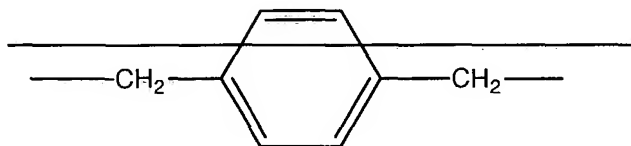


wherein n is an integer of from 0 to 20, and

R represents phenylene, naphthylene or a group represented by the following formula:



wherein A represents ~~O, S, SO₂, CO, CH₂, C(CH₃)₂~~ or a group represented by the following formula:



provided that at least one R² is not a hydrogen atom; and

R¹ represents NHR², C₁₋₆alkyl or phenyl;

~~in the above groups represented by R and A, the aromatic group can be substituted by one or more substituents selected from the group consisting of hydroxy, amino, carboxy and C₁₋₆alkyl.~~

2. Cancelled

3. (Currently Amended) A flame retarding resin composition, which comprises (A) an epoxy resin, (B) the phosphorus- and nitrogen-containing resin hardener according to claim 1 or 2, and (C) a hardening promoter.

4. (Original) The flame retarding resin composition according to claim 3, wherein said epoxy resin is selected from the group consisting of glycidyl ethers of bisphenols, glycidyl ethers of biphenols, glycidyl ethers of dihydroxybenzenes, glycidyl ethers of nitrogen-containing hetero rings, glycidyl ethers of dihydroxynaphthalene, polyglycidyl ethers of phenolics and polyglycidyl ethers of polyhydric phenols.

5. (Original) The flame retarding resin composition according to claim 3, wherein said hardening promoter is selected from the group consisting of tertiary amines, tertiary

phosphines, quaternary ammonium salts, quaternary phosphonium salts, boric trifluoride complexes, lithium compounds and imidazole compounds.

6. (Original) The flame retarding resin composition according to claim 3, wherein the amount of the component (B) hardeners is 20 to 140% of the equivalent weight of the reactive hydrogen in said hardeners, when the epoxy equivalent weight of the component (A) epoxy resin is taken as 100%.

7. (Original) The flame retarding resin composition according to claim 3, wherein the amount of the component (C) hardening promoters is from 50 to 50,000ppm, based on the total weight of said flame retarding resin composition.

8. (Original) The flame retarding resin composition according to claim 3, which further comprises other hardeners selected from the group consisting of amines, bisphenolic resin, dihydroxybenzenes, polyhydric phenolic resin and phenolics.

9. Cancelled

10. (New) A prepreg made of a flame retarding resin composition according to claim 3.

11. (New) A composite made of a flame retarding resin composition according to claim 3.

12. (New) A laminate made of a flame retarding resin composition according to claim 3.

13. (New) A printed circuit board made of a flame retarding resin composition according to claim 3.

14. (New) The flame retarding resin composition according to claim 3, wherein the composition is a substrate for build-up resin coated copper.

15. (New) The flame retarding resin composition according to claim 3, wherein the composition is an epoxy molding compound.